



# STS8DNF3LL

Dual N-channel 30V - 0.017Ω - 8A SO-8  
Low gate charge STripFET™ II Power MOSFET

## General features

Type	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STS8DNF3LL	30V	<0.020Ω	8A

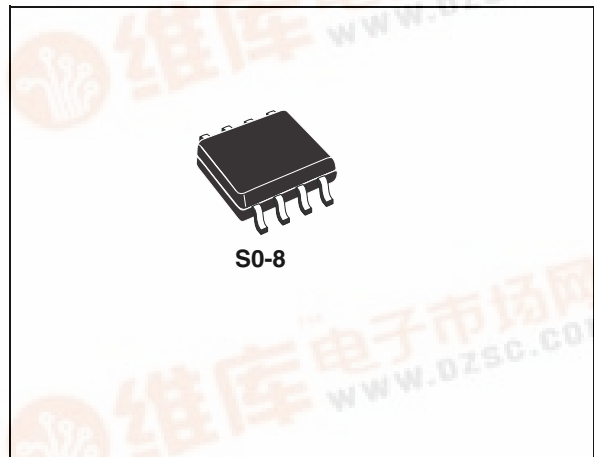
- Optimal R<sub>DS(on)</sub> x Q<sub>g</sub> trade-off @ 4.5V
- Conduction losses reduced
- Switching losses reduced

## Description

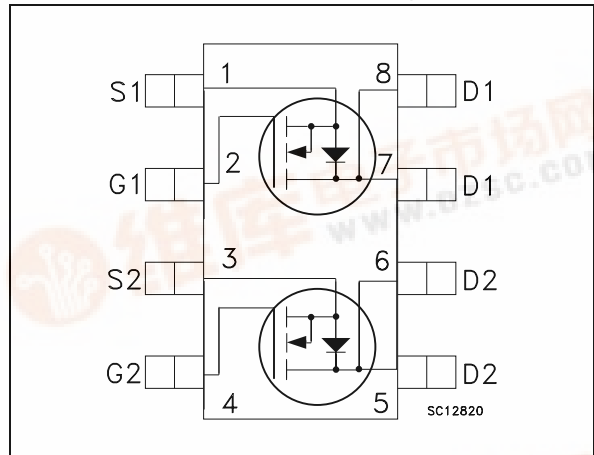
This application specific Power MOSFET is the second generation of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

## Applications

- Switching application



## Internal schematic diagram



## Order codes

Part number	Marking	Package	Packaging
STS8DNF3LL	S8DNF3LL	SO-8	Tape & reel

## Contents

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# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage ( $v_{gs} = 0$ )	30	V
$V_{GS}$	Gate- source voltage	$\pm 16$	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$ single operating	8	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$ single operating	5	A
$I_{DM}^{(1)}$	Drain current (pulsed)	32	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$ dual operating	2	W
	Total dissipation at $T_C = 25^\circ\text{C}$ single operating	1.6	W

1. Pulse width limited by safe operating area

**Table 2. Thermal data**

$R_{thj-a}$	<sup>(1)</sup> Thermal resistance junction-ambient single operating	78	$^\circ\text{C}/\text{W}$
	Thermal resistance junction-ambient dual operating	62.5	$^\circ\text{C}/\text{W}$
$T_J$	Thermal operating junction-ambient	150	$^\circ\text{C}$
$T_{stg}$	Storage temperature	-55 to 150	$^\circ\text{C}$

1. Mounted on FR-4 board with 0.5 in<sup>2</sup> pad of Cu.

## 2 Electrical characteristics

( $T_{CASE}=25^{\circ}C$  unless otherwise specified)

**Table 3. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 250 \mu A, V_{GS} = 0$	30			V
$I_{DSS}$	Zero gate voltage Drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$			1	$\mu A$
		$V_{DS} = \text{Max rating},$ $T_C = 125^{\circ}C$			10	$\mu A$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 16V$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1			V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10V, I_D = 4A$		0.017	0.020	$\Omega$
		$V_{GS} = 4.5V, I_D = 4A$		0.020	0.024	$\Omega$

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} = 15V, I_D = 4 A$		12.5		S
$C_{iss}$	Input capacitance	$V_{DS} = 25V, f = 1 \text{ MHz},$ $V_{GS} = 0$		800		pF
$C_{oss}$	Output capacitance			250		pF
$C_{rss}$	Reverse transfer capacitance			60		pF
$Q_g$	Total gate charge	$V_{DD} = 15V, I_D = 8A,$ $V_{GS} = 5V$ (see Figure 14)		12.5	17	nC
$Q_{gs}$	Gate-source charge			3.2		nC
$Q_{gd}$	Gate-drain charge			4.5		nC

1. Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5.

**Table 5. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Turn-on delay time	$V_{DD} = 15 V, I_D = 4A,$ $R_G = 4.7\Omega, V_{GS} = 4.5V$ (see Figure 13)		18		ns
	Rise time			32		ns
$t_{d(off)}$ $t_f$	Turn-off Delay Time	$V_{DD} = 15 V, I_D = 4A,$ $R_G = 4.7\Omega, V_{GS} = 4.5V$ (see Figure 13)		21		ns
	Fall Time			11		ns

**Table 6. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$I_{SD}$	Source-drain current				8	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				32	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 8A, V_{GS} = 0$			1.2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 8A, V_{DD} = 15V$ $di/dt = 100A/\mu s,$ $T_J = 150^\circ C$ (see Figure 15)		23		ns
$Q_{rr}$	Reverse recovery charge			17		nC
$I_{RRM}$	Reverse recovery current			1.5		A

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

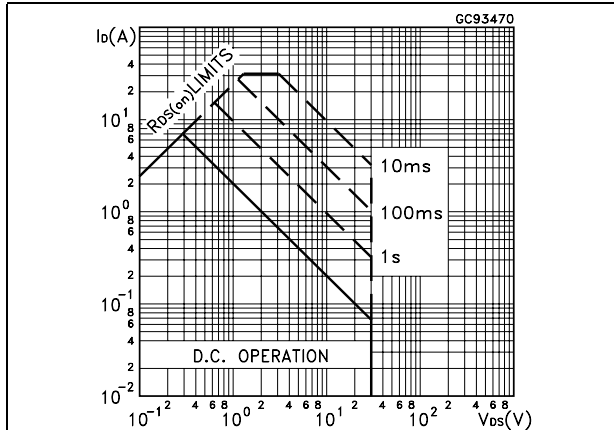


Figure 2. Thermal impedance

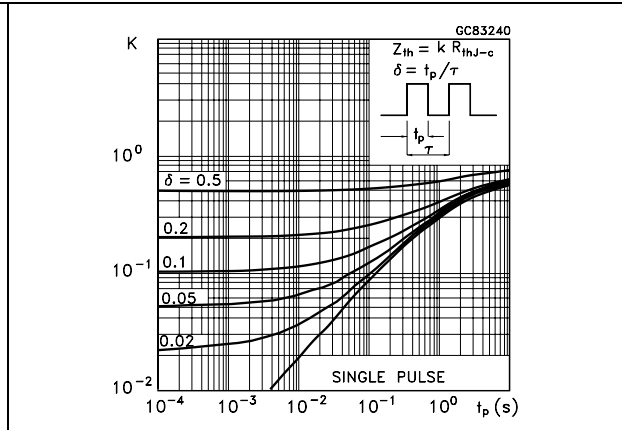


Figure 3. Output characteristics

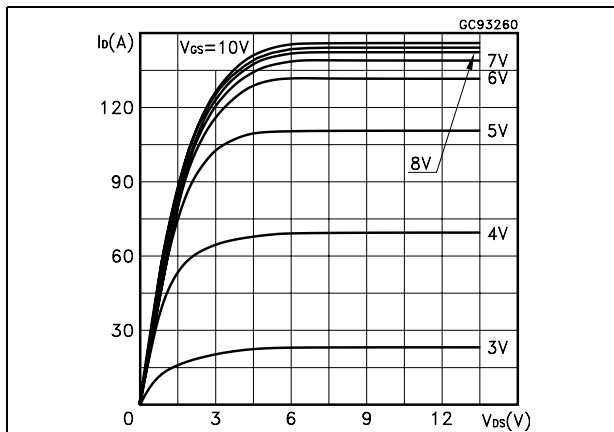


Figure 4. Transfer characteristics

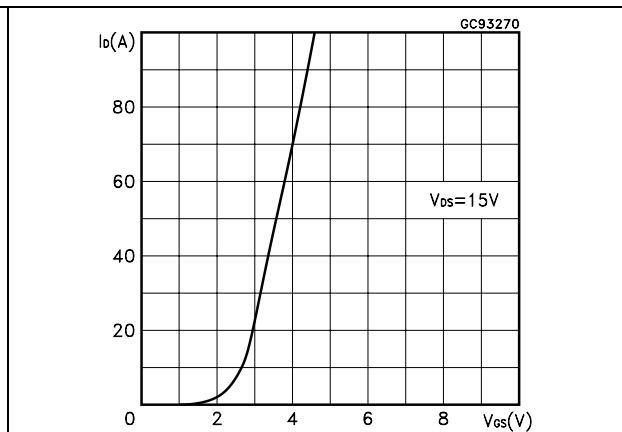


Figure 5. Transconductance

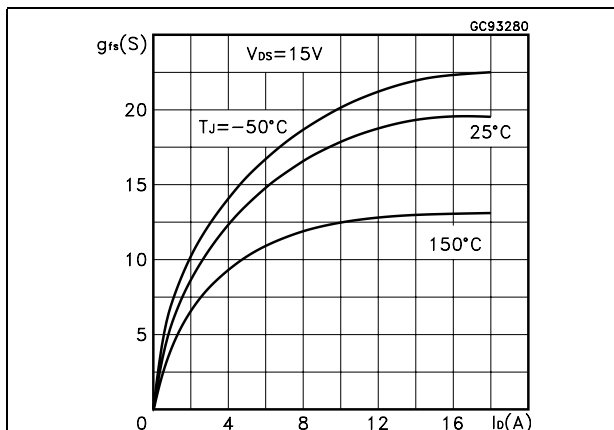


Figure 6. Static drain-source on resistance

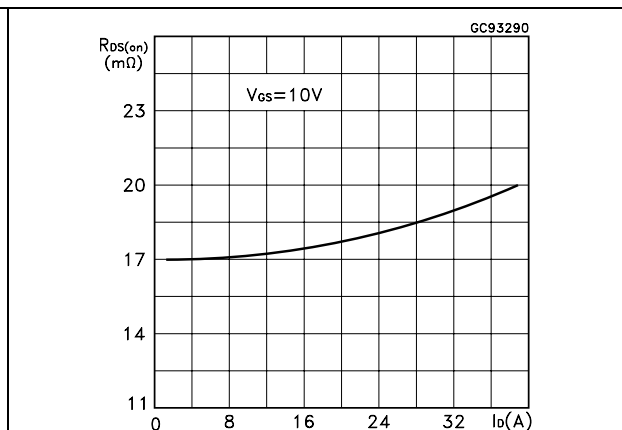


Figure 7. Gate charge vs. gate-source voltage Figure 8. Capacitance variations

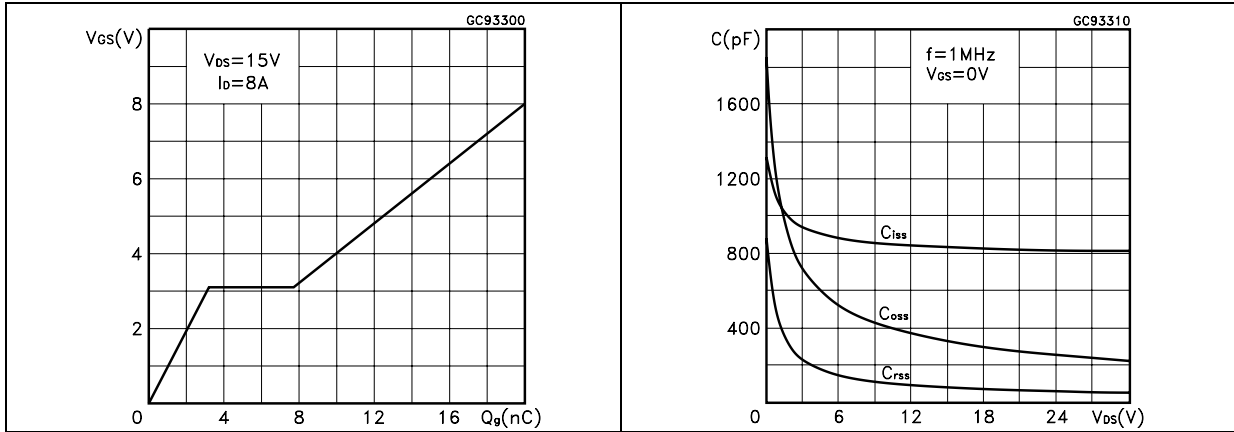


Figure 9. Normalized gate threshold voltage vs. temperature Figure 10. Normalized on resistance vs. temperature

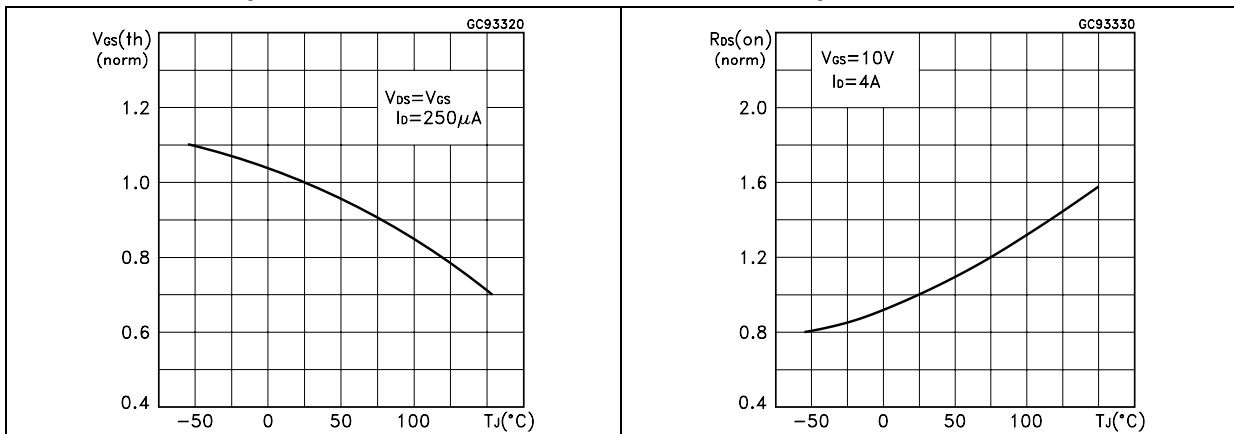
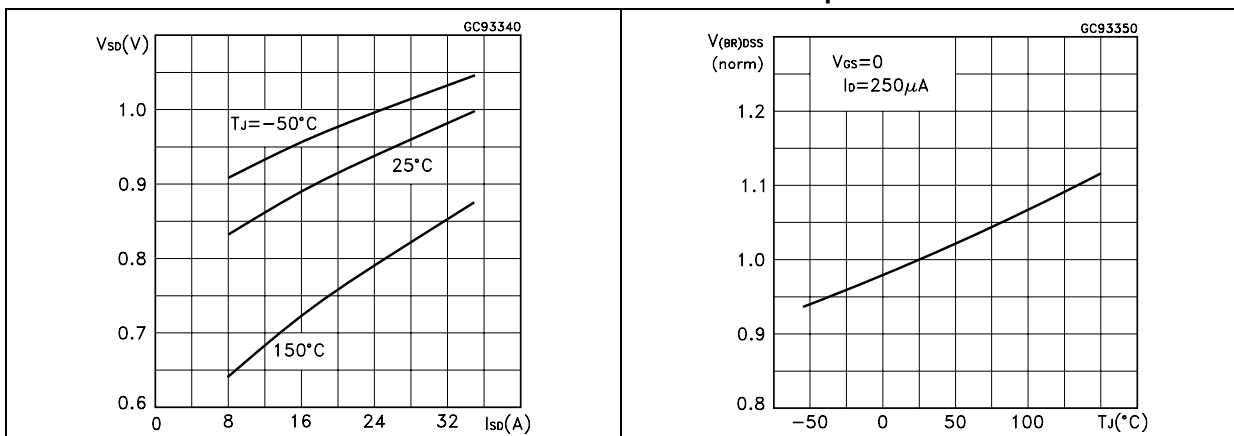


Figure 11. Source-drain diode forward characteristics Figure 12. Normalized breakdown voltage vs. temperature



### 3 Test circuit

Figure 13. Switching times test circuit for resistive load

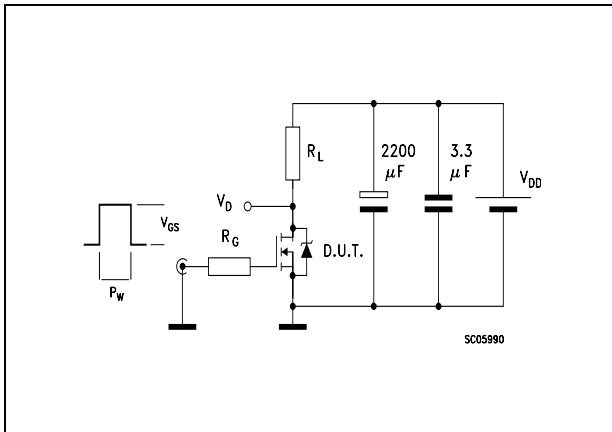


Figure 14. Gate charge test circuit

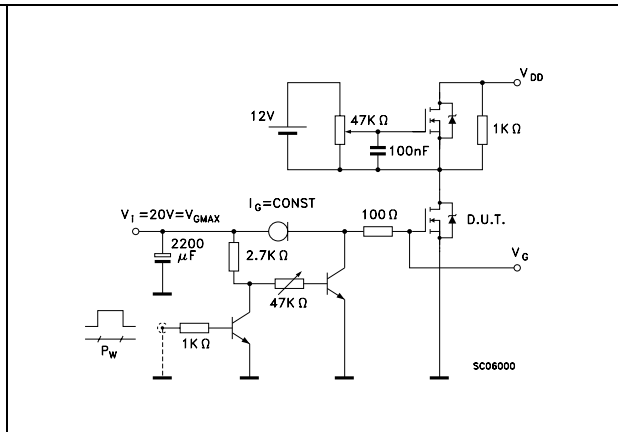


Figure 15. Test circuit for inductive load switching and diode recovery times

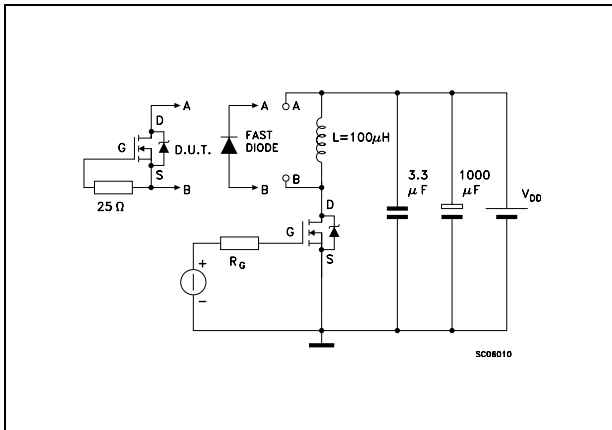


Figure 16. Unclamped Inductive load test circuit

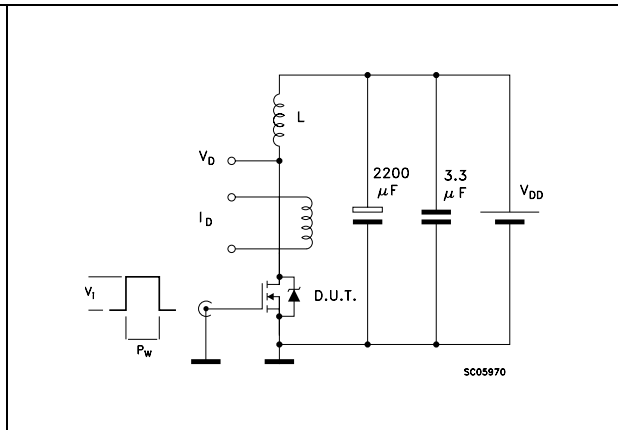


Figure 17. Unclamped inductive waveform

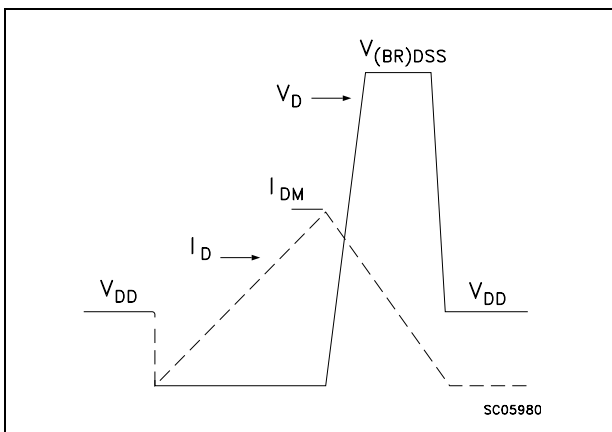
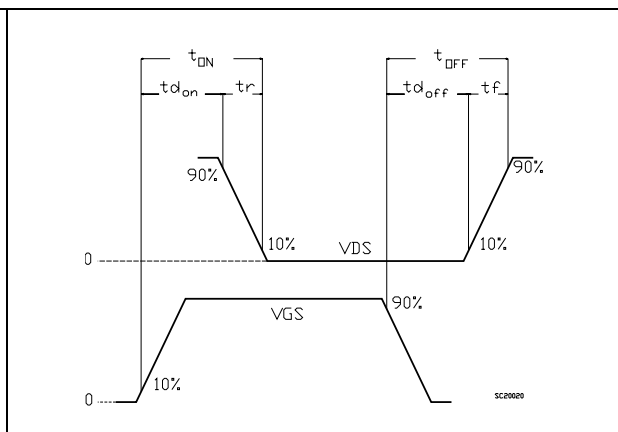


Figure 18. Switching time waveform



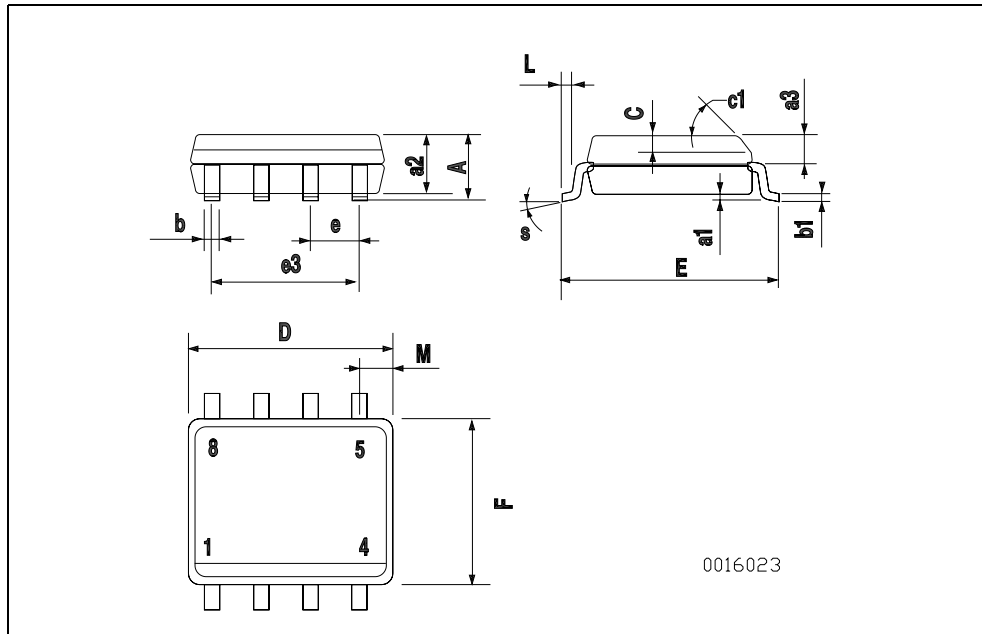


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at : [www.st.com](http://www.st.com)

**SO-8 MECHANICAL DATA**

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c1	45 (typ.)					
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S	8 (max.)					



## 5 Revision history

**Table 7. Revision history**

Date	Revision	Changes
11-Sep-2006	8	Complete document
15-Nov-2006	9	The document has been reformatted
30-Jan-2007	10	Typo mistake on <a href="#">Table 1</a> .

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